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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: St ve M. Danziger, et al.

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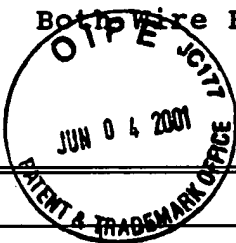
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2829

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Examiner: TO BE ASSIGNED

E. Pert

For: Method and Apparatus for Evaluating a Known Good Die Using  
Both Wire Bond and Flip-Chip Interconnects

## PTO FORM 1449 SUBMISSION

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OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS		
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Examiner Signature	Evan Pert	Date Considered	9-15-02
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\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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